

APPLICATION OF COPPER SLAGAS OPTIONAL FILLER IN MICROSURFACING

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ABSTRACT

Copper slag is generated during pyro metallurgical production of copper from copper ores contains materials like calcium oxide, iron, alumina, silica etc. for Pertonne of metal production about 2.2 ton of slag is generated. In this research experimental investigation is carried out to analyze suitability of copper slag as alternative filler for an option of cement in microsurfacing. Microsurfacing is a one of the preventive maintenance technique extensively used, in India. The present paper describes results of experimental investigation of microsurfacing mix obtained by using alternative filler as copper slag as a substitute of OPC. In this experimental investigation breaking time of the emulsion, the cohesion and the abrasion resistance of microsurfacing material with copper slag as filler is examined. The outcomes show that copper slag can be suitable alternative filler for microsurfacing technology as compare to OPC. The use copper slag as alternative filler, make microsurfacing technology cost-effective and environmental friendly.

KEYWORDS: Copper Slag, Slurry Seal, Micro Surfacing